



CTC APPROVAL CODE		30070PC4		DWG NO PKGS00005		REV E		Garsonm Your Technology Partner	
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E	LEAD WIDTH	3000-008-11	SI 100	TOLERANCES (INCH/MIL)		FINISHING		SCALE 20:1		TITLE	
D	EXPOSED PAD OPTION	3000-008-11	SI 100	±	FRAC	✓	ORIGINATOR	TOOLING DEPT MANAGER		MINI SOIC 10LD	
C	CHANGED LOGO	3000-008-08	SI 100	±	DECIMALS	⊕	ENGINEERING MANAGER	ENGINEERING MANAGER		PACKAGE OUTLINE	
REV POS	DESCRIPTION	DATE	BY	APPD	±	ANGLE	STYMBOL	QA DEPT MANAGER		REF : CUSTOMER SPECIFICATION	
					±	XXXX		CTC DESIGN DEPT MANAGER		SHEET NO : 1 OF 2	

MINI SOIC 10LD			MINI SOIC 10LD - EP1		
SYMBOL	PACKAGE OUTLINE (MILLIMETER)		SYMBOL	PACKAGE OUTLINE (MILLIMETER)	
		±TOL			±TOL
A	1.10	MAX	A	1.10	MAX
A1	0.10	±0.05	A1	0.10	±0.05
A2	0.86	±0.08	A2	0.86	±0.08
D	3.00	±0.10	D	3.00	±0.10
D2	2.95	±0.10	D2	2.95	±0.10
E	4.90	±0.15	E	4.90	±0.15
E1	3.00	±0.10	E1	3.00	±0.10
E2	2.95	±0.10	E2	2.95	±0.10
E3	0.51	±0.13	E3	0.51	±0.13
E4	0.51	±0.13	E4	0.51	±0.13
R	0.15	+0.15 -0.08	R	0.15	+0.15 -0.08
R1	0.15	+0.15 -0.08	R1	0.15	+0.15 -0.08
t1	0.31	±0.08	t1	0.31	±0.08
t2	0.41	±0.08	t2	0.41	±0.08
b	0.23	+0.07 -0.06	b	0.23	+0.07 -0.06
b1	0.20	±0.03	b1	0.20	±0.03
c	0.18	±0.05	c	0.18	±0.05
c1	0.15	+0.03 -0.02	c1	0.15	+0.03 -0.02
Ø1	3.0°	±3.0°	Ø1	3.0°	±3.0°
Ø2	12.0°	±3.0°	Ø2	12.0°	±3.0°
Ø3	12.0°	±3.0°	Ø3	12.0°	±3.0°
L	0.55	±0.15	L	0.55	±0.15
L1	0.95 BSC	—	L1	0.95 BSC	—
aaa	0.10	—	aaa	0.10	—
bbb	0.08	—	bbb	0.08	—
ccc	0.25	—	ccc	0.25	—
e	0.50 BSC	—	e	0.50 BSC	—
S	0.50 BSC	—	S	0.50 BSC	—
D3	2.18	±0.10	D3	2.18	±0.10
E5	1.73	±0.10	E5	1.73	±0.10

NOTES :

1. ALL DIMENSIONS ARE IN MILLIMETERS (ANGLE IN DEGREES), UNLESS OTHERWISE SPECIFIED.
2. DATUMS **-B-** AND **-C-** TO BE DETERMINED AT DATUM PLANE **-H-**.
3. DIMENSIONS "D" AND "E1" ARE TO BE DETERMINED AT DATUM PLANE **-H-**.
4. DIMENSIONS "D2" AND "E2" ARE FOR TOP PACKAGE AND DIMENSIONS "D" AND "E1" ARE FOR BOTTOM PACKAGE.
5. CROSS SECTION A-A TO BE DETERMINED AT 0.13 TO 0.25 MM FROM THE LEAD TIP.
6. DIMENSIONS "D" AND "D2" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS.
7. DIMENSIONS "E1" AND "E2" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
8. EXPOSED PAD FEATURE IS PRESENT ON VARIATIONS DESIGNATED WITH "-EP"

CTC APPROVAL CODE		30070PC4		DWG NO		PKGS00005		REV		E	
E	—	LEAD WIDTH	3006-10R-17	REF. L00	TOLERANCES (INCH/MIL)		FINISHING	SCALE	20:1		
D	—	EXPOSED PAD OPTION	3006-14R-17	REF. L00	FRAC	DECIMALS		ORIGINATOR	TITLE		
C	—	CHANGED LOGO	3006-10R-03	REF. L00	±	X XX XXX XXXX		TOOLING DEPT MANAGER	MINI SOIC 10LD		
REV	POS	DESCRIPTION	DATE	BY	APPD	±	ANGLE	ENGINEERING MANAGER	PACKAGE OUTLINE		
								QA DEPT MANAGER	REF : CUSTOMER SPECIFICATION		
								CTC DESIGN DEPT MANAGER	SHEET NO : 2 OF 2		

